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<p>Substitute for form 1449A/PTO</p> <h1>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</h1> <p>(use as many sheets as necessary)</p>				<b><i>Complete if Known</i></b>	
				Application Number	Unknown
				Filing Date	(Herewith)
				First Named Inventor	Efren M. Lacap
				Art Unit	Unknown
				Examiner Name	Unknown
Sheet	1	of	2	Attorney Docket Number	408204

## **U.S. PATENT DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code <sup>2</sup> (if known)			
	1	US-5,553,769	09-10-1996	Ellerson et al.	
	2	US- 4,604,644	08-05-1986	Beckham et al.	
	3	US- 5,316,205	05-31-1994	Melton	
	4	US- 5,918,792	07-06-1999	Stumpe et al.	
	5	US- 6,278,264	08-21-2001	Burstein et al.	
	6	US- 6,445,244	09-03-2002	Stratakos et al.	
	7	US- 6,400,126	06-04-2002	Zuniga et al.	
	8	US- 6,498,467	12-24-2002	Stratakos	
	9	US- 6,445,169	09-03-2002	Schultz et al.	
	10	US- 6,443,614	08-13-614	You et al.	
	11	US- 6,462,522	10-08-2002	Burstein et al.	
	12	US- 6,020,729	02-01-2000	Stratakos et al.	
	13	US- 6,225,795	05-01-2001	Stratakos et al.	
	14	US- 3,429,040	02-25-1969	Miller	
	15	US- 3,401,126	09-10-1968	Miller et al.	
	16	US- T955,008	02-01-1977	Gregor et al.	
		US-			

## **FOREIGN PATENT DOCUMENTS**

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional). 2 See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. 3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. 6 Applicant is to place a check mark here if English language Translation is attached.

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				Group Art Unit	Unknown
				Examiner Name	Unknown
Sheet	2	of	2	Attorney Docket Number	408204

**OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
	1	Figures 1, and 3-6 from "Oki technical Review", <a href="http://www.oki.com/en/otr/html/nf/">http://www.oki.com/en/otr/html/nf/</a> , February 19, 2003, 5 pages	
	2	"Flip chip photographs of flip chip bumps, flip chip assemblies, flip chip interconnections", Flipchips dot com, <a href="http://www.flipchips.com/photos.html">http://www.flipchips.com/photos.html</a> , February 13, 2003, 3 pages	
	3	"Flip-chip Packaging: a 32-Year-Old Infant Grows Up", Chip Scale Review Online, <a href="http://www.chipscalereview.com/issues/0701/fl_01.html">http://www.chipscalereview.com/issues/0701/fl_01.html</a> , July, 2001, pp. 1-4	
	4	"Flip-chip Packaging: a 32-Year-Old Infant Grows Up", Chip Scale Review Online, <a href="http://www.chipscalereview.com/issues/0701/fl_02.html">http://www.chipscalereview.com/issues/0701/fl_02.html</a> , July, 2001, pp. 1-5	
	5	"The Emerging Copper Revolution Will Impact ICs with Critical Dimensions 100nm", Chip Scale Review Online, <a href="http://www.chipscalereview.com/Issues/0301/techReport.html">http://www.chipscalereview.com/Issues/0301/techReport.html</a> , March, 2001, pp. 1-3	
	6	"Making Microchips", <a href="http://www.glenco.com/norton/n-instructor-/updates/2000/21100-7.html">http://www.glenco.com/norton/n-instructor-/updates/2000/21100-7.html</a> , February 19, 2003, pp. 1-4	
	7	"Process Defect Guides", ppm-monitoring.com, <a href="http://www.thepdfshop.com.uk/ppm/asp/wave.asp">http://www.thepdfshop.com.uk/ppm/asp/wave.asp</a> , July 2, 2003, 4 pages	
	8	"300mm Wafer Bumping", Technology Publishing - A division of Montgomery Research Europe Ltd., <a href="http://www.future-fab.com/documents.asp?grID=217&amp;d_ID=1338">http://www.future-fab.com/documents.asp?grID=217&amp;d_ID=1338</a> , July 1, 2003, 6 pages	
	9	XICOR, "CSP Packaging Technology ("B" Package Option)", Revised March, 2003, 11 pages, XICOR, Milpitas, CA	
	10	JASPER, JORG, "From Direct Chip Attach to Wafer Level CSP - A Modular Appropach to Serve Customer Needs", 5 pages, EM -Marin S.A.	
	11	BICE, SHANNON B. and LI, YUZHOU, "Chemical Mechanical Polishing (CMP) for Computer Chip Manufacturing", 3 pages.	
	12	ELENIUS, PETER, "The UltraCSP™ Wafer Scale Package", 6 pages, Flip Chip Technologies, Phoenix, AZ	
	13	"STAYCHIP™ 3075F Underfill for Handheld Electronic Devices & System-in-Package", 15 pages, Cookson Electronics Semiconductor Products, Alpharetta, GA	
	14	DURAH, DR. HAMIT, "Chip-on-Foil: An Emerging Technology for Display Driver Electronics", October 10, 2002, 33 pages, Phillips Semiconductors Zurich	
	15	FJELSTAD, JOSEPH, "Wafer Level Packaging of Compliant CSPs Using Flexible Film Interposers", HDI Magazine, Spring 1999, 6 pages	
	16	"Flip Chip Packaging for SRAM", Copyright 1999, 2 pages, IBM USA	
Examiner Signature		Date Considered	

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